| Title of Change: | MT9V115 Datasheet Update. |
|---|---|
| Effective date: | 25 July 2018 |
| Contact information: | Contact your local ON Semiconductor Sales Office or <Sonya.Yip@onsemi.com> |
| Type of notification: | This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin. |
| Change Category: | ☐ Wafer Fab    ☐ Assembly Change    ☐ Test Change    ☑ Other    <u>Documentation</u> |

**Change Sub-Category(s):**

☐ Manufacturing Site Addition     ☐ Material Change          ☑ Datasheet/Product Doc change

☐ Manufacturing Site Transfer     ☐ Product specific change   ☐ Shipping/Packaging/Marking

☐ Manufacturing Process Change                                ☐ Other: _____

| Sites Affected: | ON Semiconductor Sites: None | External Foundry/Subcon Sites: None |
|---|---|---|

**Description and Purpose:**

MT9V115 Datasheet was updated to correct a documentation error. These changes do not affect form, fit, or function of the product.

**MT9V115 Datasheet Changes**

1. Removed "Table 25, Package Dimensions".

    **Old Table 25:**

Table 25. PACKAGE DIMENSION

| Parameter | Symbol | CPK | Nominal | Min | Max | Nominal | Min | Max |
|---|---|---|---|---|---|---|---|---|
| | | | Millimeters | | | Inches | | |
| Package Body Dimension X | A | Yes | 2.69355 | 2.66855 | 2.71855 | 0.10605 | 0.10506 | 0.10703 |
| Package Body Dimension Y | B | Yes | 2.69355 | 2.66855 | 2.71855 | 0.10605 | 0.10506 | 0.10703 |
| Package Height | C | Yes | 0.700 | 0.655 | 0.745 | 0.02756 | 0.02579 | 0.02933 |
| Cavity height (Glass to Pixel Distance) | C4 | Yes | 0.041 | 0.037 | 0.045 | 0.00161 | 0.00146 | 0.00177 |
| Glass Thickness | C3 | | 0.400 | 0.390 | 0.410 | 0.01575 | 0.01535 | 0.01614 |
| Package Body Thickness | C2 | | 0.570 | 0.535 | 0.605 | 0.02244 | 0.02106 | 0.02382 |
| Ball Height | C1 | Yes | 0.130 | 0.110 | 0.150 | 0.00512 | 0.00433 | 0.00591 |
| Ball Diameter | D | Yes | 0.200 | 0.180 | 0.220 | 0.00787 | 0.00709 | 0.00866 |
| Total Ball Count | N | | 25 | | | | | |
| Ball Count X Axis | N1 | | 5 | | | | | |
| Ball Count Y Axis | N2 | | 5 | | | | | |
| UBM | U | Yes | 0.240 | 0.230 | 0.250 | 0.00945 | 0.00906 | 0.00984 |
| Pins Pitch X Axis | J1 | | 0.500 | 0.490 | 0.510 | 0.01969 | 0.01929 | 0.02008 |
| Pins Pitch Y Axis | J2 | | 0.500 | 0.490 | 0.510 | 0.01969 | 0.01929 | 0.02008 |
| BGA Ball Center to Package Center Offset | X | | 0 | −0.025 | 0.025 | 0 | −0.00098 | 0.00098 |
| BGA Ball Center to Package Center Offset | Y | | 0 | −0.025 | 0.025 | 0 | −0.00098 | 0.00098 |
| Edge to Ball Center Distance Along X | S1 | | 0.347 | 0.317 | 0.377 | 0.01365 | 0.01247 | 0.01483 |
| Edge to Ball Center Distance Along Y | S2 | | 0.347 | 0.317 | 0.377 | 0.01365 | 0.01247 | 0.01483 |

**2.** Added "Table 25, Ball Matrix for Parallel Mode" and "Table 26, Ball Matrix for MIPI mode".

New Table 25:

Table 25. BALL MATRIX FOR PARALLEL MODE

|   | 1 | 2 | 3 | 4 | 5 |
|---|---|---|---|---|---|
| A | VPP | STANDBY | D0 | GND_PLL | D3 |
| B | AGND | PIXCLK | D1 | D2 | D5 |
| C | VDD | VAA[1] | CLK | D4 | VDD_IO |
| D | GND[2] | LINE_VALID | D7 | VDD_PHY | SDATA |
| E | FRAME_VALID | D6 | SCLK | VDD | GND |

New Table 26:

Table 26. BALL MATRIX FOR MIPI MODE

|   | 1 | 2 | 3 | 4 | 5 |
|---|---|---|---|---|---|
| A | VPP | STANDBY | D0 | GND_PLL | D3 |
| B | AGND | PIXCLK | D1 | D2 | D5 |
| C | VDD | VAA[1] | CLK | D4 | VDD_IO |
| D | GND[2] | CLK_N | DATA_P | VDD_PHY | SDATA |
| E | CLK_P | DATA_N | SCLK | VDD | GND |

2.  VAA and VDD_PLL tied in the CSP.
3.  GND_PLL and DGND tied in the CSP.

**List of Affected Parts:**

MT9V115D00STCK22EC1-200
MT9V115EBKSTC-CR
MT9V115W00STCK22EC1-750

## Appendix A: Changed Products

D

| Product | Customer Part Number |
|---|---|
| MT9V115EBKSTC-CR | |